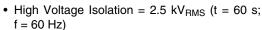


2SK2933-VB Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60	1		
R _{DS(on)} (Ω)	V _{GS} = 10 V	0.027		
Q _g (Max.) (nC)	95	95		
Q _{gs} (nC)	27			
Q _{gd} (nC)	46			
Configuration	Single			

FEATURES

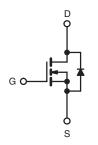
Isolated Package





- Sink to Lead Creepage Distance = 4.8 mm
- 175 °C Operating Temperature
- · Dynamic dV/dt Rating
- · Low Thermal Resistance
- Lead (Pb)-free Available





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherw PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	60	,,	
Gate-Source Voltage			V _{GS}	± 20	V	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	- I _D	45	А	
		T _C = 100 °C		30		
Pulsed Drain Current ^a			I _{DM}	220	-	
Linear Derating Factor				0.32	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ	
Maximum Power Dissipation	T _C =	T _C = 25 °C		52	W	
Peak Diode Recovery dV/dtc	•		dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s			300 ^d		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=25$ V, starting $T_J=25$ °C, L=129 $\mu H,~R_G=25$ $\Omega,~I_{AS}=30$ A (see fig. 12). c. $I_{SD}\leq 52$ A, $dI/dt\leq 250$ A/ $\mu s,~V_{DD}\leq V_{DS},~T_J\leq 175$ °C.

- d. 1.6 mm from case.



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.1	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	60	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	-	0.060	-	V/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	1.0	-	3.0	V	
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zana Oata Wallana Busin Oamani		V _{DS} = 60 V, V _{GS} = 0 V		-	-	25	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48 V	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 18 A ^b	-	0.027	-	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 25 V, I _D = 18 A ^b		15	-	-	S
Dynamic							•
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$ $f = 1.0 \text{ MHz}$		-	1500	-	- pF
Output Capacitance	C _{oss}			-	720	-	
Reverse Transfer Capacitance	C _{rss}			-	100	-	
Drain to Sink Capacitance	С			-	12	-	
Total Gate Charge	Qg		I _D = 52 A, V _{DS} = 48 V, see fig. 6 and 13 ^b	-	-	95	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		-	-	27	
Gate-Drain Charge	Q _{gd}	1		-	-	46	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 30 \text{ V}, I_{D} = 52 \text{ A},$ $R_{G} = 9.1 \Omega, R_{D} = 0.54 \Omega,$ see fig. 10^{b}		-	19	-	- ns
Rise Time	t _r			-	120	-	
Turn-Off Delay Time	t _{d(off)}			-	55	-	
Fall Time	t _f			-	86	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal Source Inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	45	- A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	120	
Body Diode Voltage	V_{SD}	T _J = 25 °C, I _S = 30 A, V _{GS} = 0 V ^b		-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	— T _J = 25 °C, I _F = 52 A, dl/dt = 100 A/μs ^b		-	140	300	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	1.2	2.8	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	n-on is dominated by L_S and L_D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

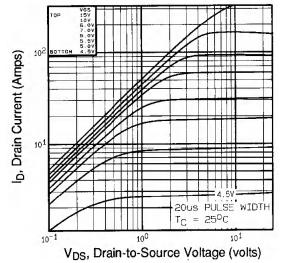


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

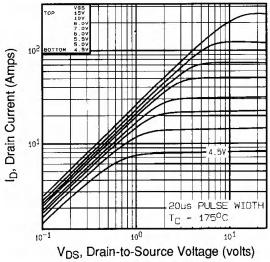


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

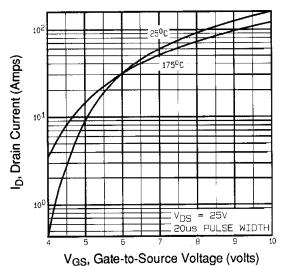


Fig. 3 - Typical Transfer Characteristics

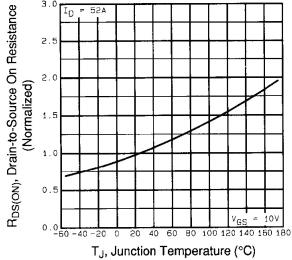


Fig. 4 - Normalized On-Resistance vs. Temperature



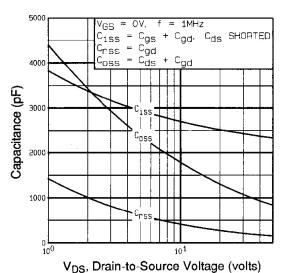


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

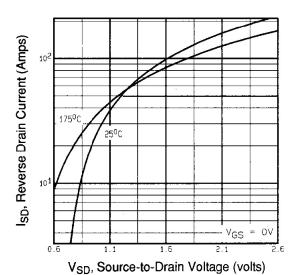


Fig. 7 - Typical Source-Drain Diode Forward Voltage

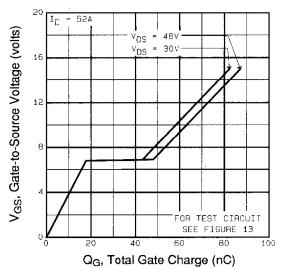


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

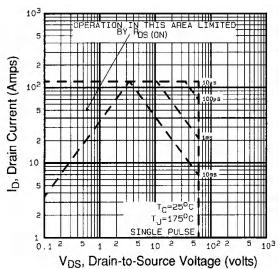


Fig. 8 - Maximum Safe Operating Area



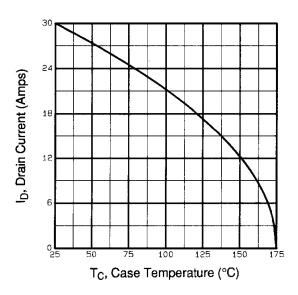


Fig. 9 - Maximum Drain Current vs. Case Temperature

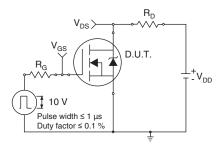


Fig. 10a - Switching Time Test Circuit

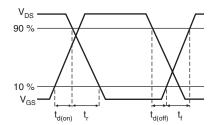


Fig. 10b - Switching Time Waveforms

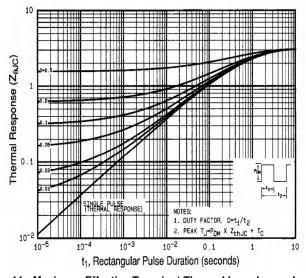


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

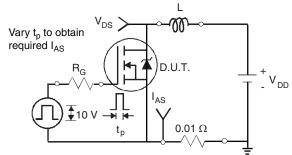


Fig. 12a - Unclamped Inductive Test Circuit

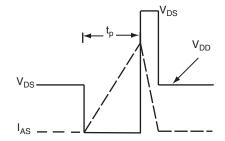
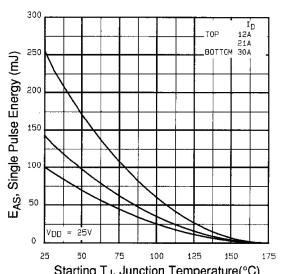


Fig. 12b - Unclamped Inductive Waveforms





 $Starting \ T_J, \ Junction \ Temperature (^{\circ}C)$ Fig. 12c - Maximum Avalanche Energy vs. Drain Current

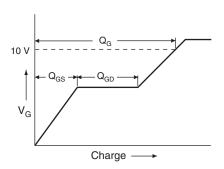


Fig. 13a - Basic Gate Charge Waveform

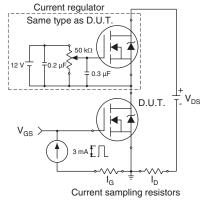
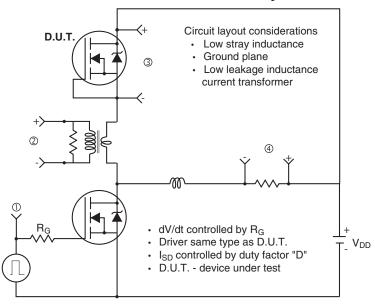
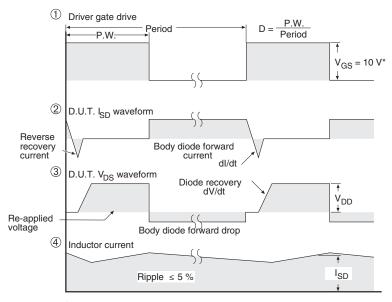


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit





* $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13
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